LN62S

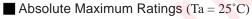
GaAs Infrared Light Emitting Diode

For optical control systems

This product can be combined with various types of silicon photodetectors such as the PN120S to form optical controllers.

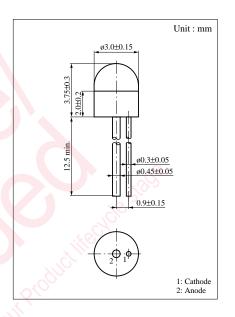
Features

- High-power output, high-efficiency : $P_O = 3.5 \text{ mW (typ.)}$
- Infrared light emission close to monochromatic light : $\lambda_P = 950 \text{ nm}$ (typ.)
- Small ceramic package



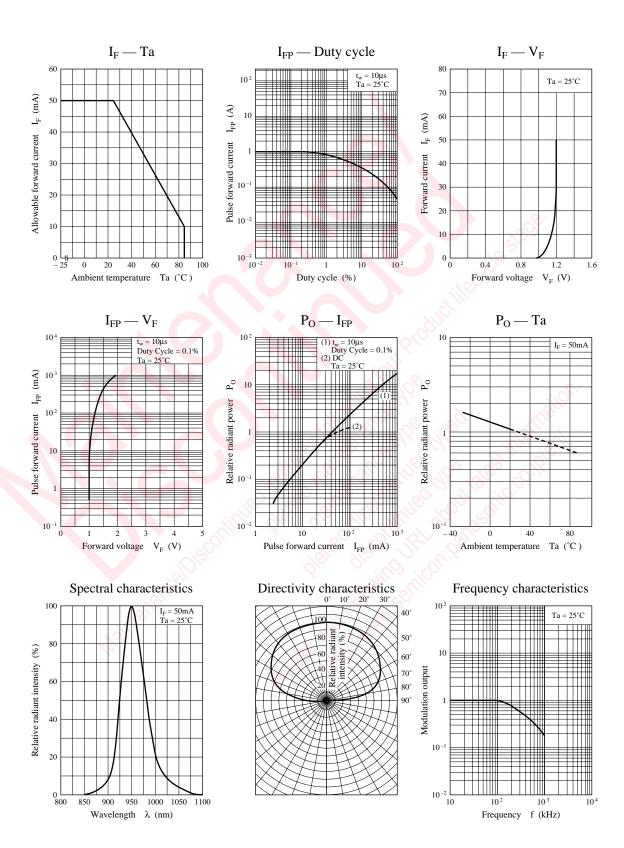
Parameter	Symbol	Ratings	Unit	
Power dissipation	P_{D}	75	mW	
Forward current (DC)	I_{F}	50	mA	
Pulse forward current	${ m I_{FP}}^*$	1	A	
Reverse voltage (DC)	V _R	3	V	
Operating ambient temperature	T_{opr}	-25 to +85	°C)°	
Storage temperature	T_{stg}	-30 to +100	°C	

^{*} f = 100 Hz, Duty cycle = 0.1 %



■ Electro-Optical Characteristics (Ta = 25°C)

			4			
Parameter	Symbol	Conditions	min	typ	max	Unit
Radiant power	P _O	$I_F = 50 \text{mA}$	1.5	3.5		mW
Peak emission wavelength	λ_{P}	$I_F = 50 \text{mA}$		950		nm
Spectral half band width	Δλ	I _F = 50mA		50		nm
Forward voltage (DC)	V _F	I _F = 50mA		1.2	1.5	V
Reverse current (DC)	I_R	$V_R = 3V$			10	μΑ
Capacitance between pins	Ct	$V_R = 0V$, $f = 1MHz$		50		pF
Half-power angle	θ	The angle in which radiant intencity is 50%		80		deg.



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■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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